

IN THE SPECIFICATION

In the specification, please replace ¶ [0045] with the following marked-up paragraph:

[0045] In a further variant (FIGS. 14 and 15), all of the caps are integral with one another and form a continuous cap wafer with depressions 316 therein such that the main surface 312 of wafer 310 is exposed only within spaced-apart depressions 316. Stated another way, the upper or capping wafer 314 defines a continuous upper surface 303 whereas the contacts 322 of the wafer are disposed of at a lower level defined by the main surface 312 in depressions 316. The terminal-bearing element 330 is mounted on the upper surface 303. The terminals 336 on the terminal-bearing element are connected by leads connecting downwardly into the depression 316, to the contacts 322 at the main surface or level 312. As shown in FIG. 15, the depression 316 has walls 370 extending away from the main surface 312 of wafer 310. The contacts 322 have edges 372 and the edges 372 which are adjacent to a wall 370 are spaced apart from the wall.

Also, in this arrangement the leads are formed by wire bonds 338 added in a separate operation, after application of the terminal-bearing element 330. Here again, the wafer can be severed by cutting along severance lines 362 (FIG. 15) to form individual units. The severance lines need not extend through the depressions 316. Stated another way, in the finished units, the contacts 322 and leads 338 do not lie at the edges of the unit.